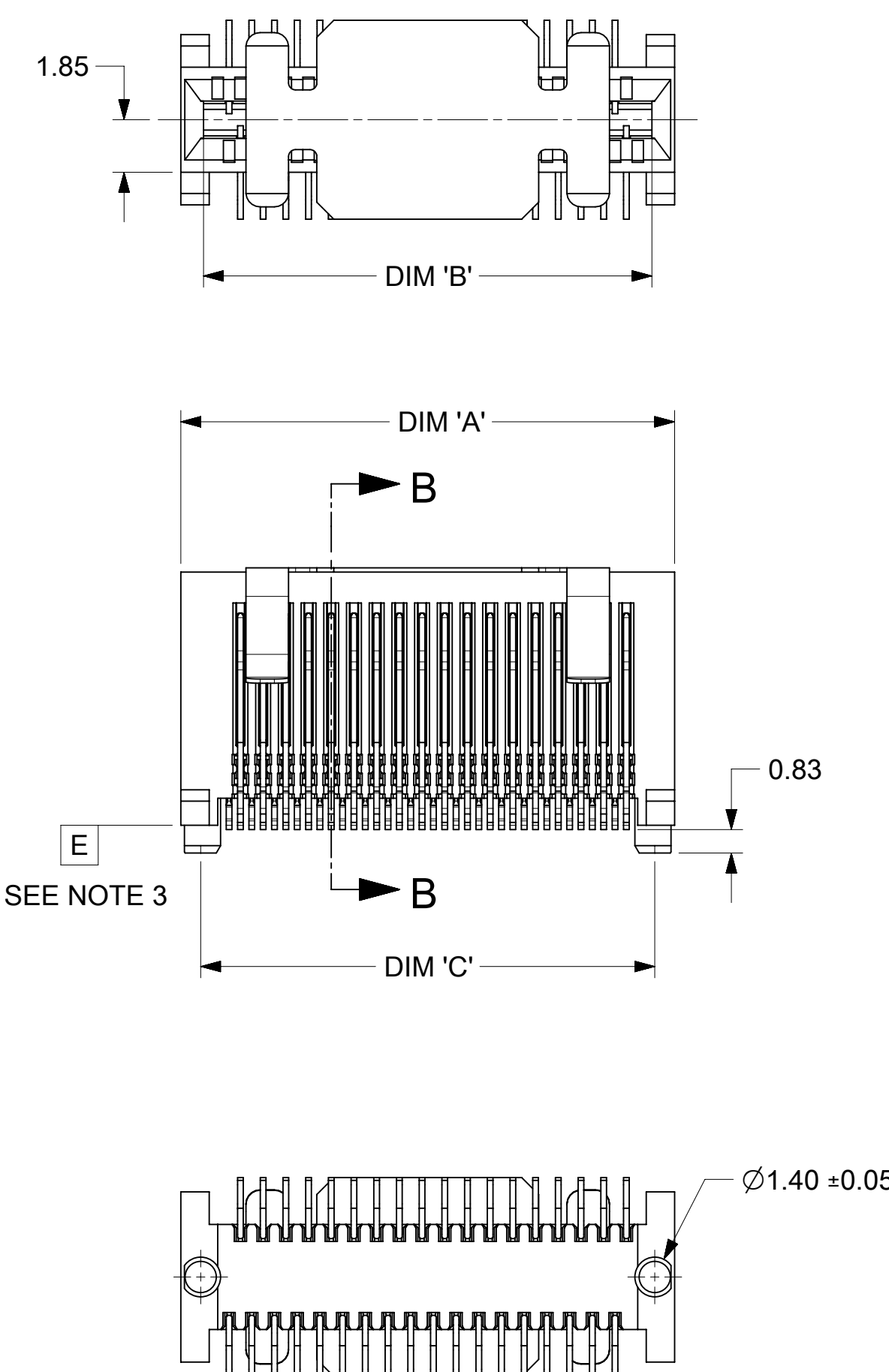
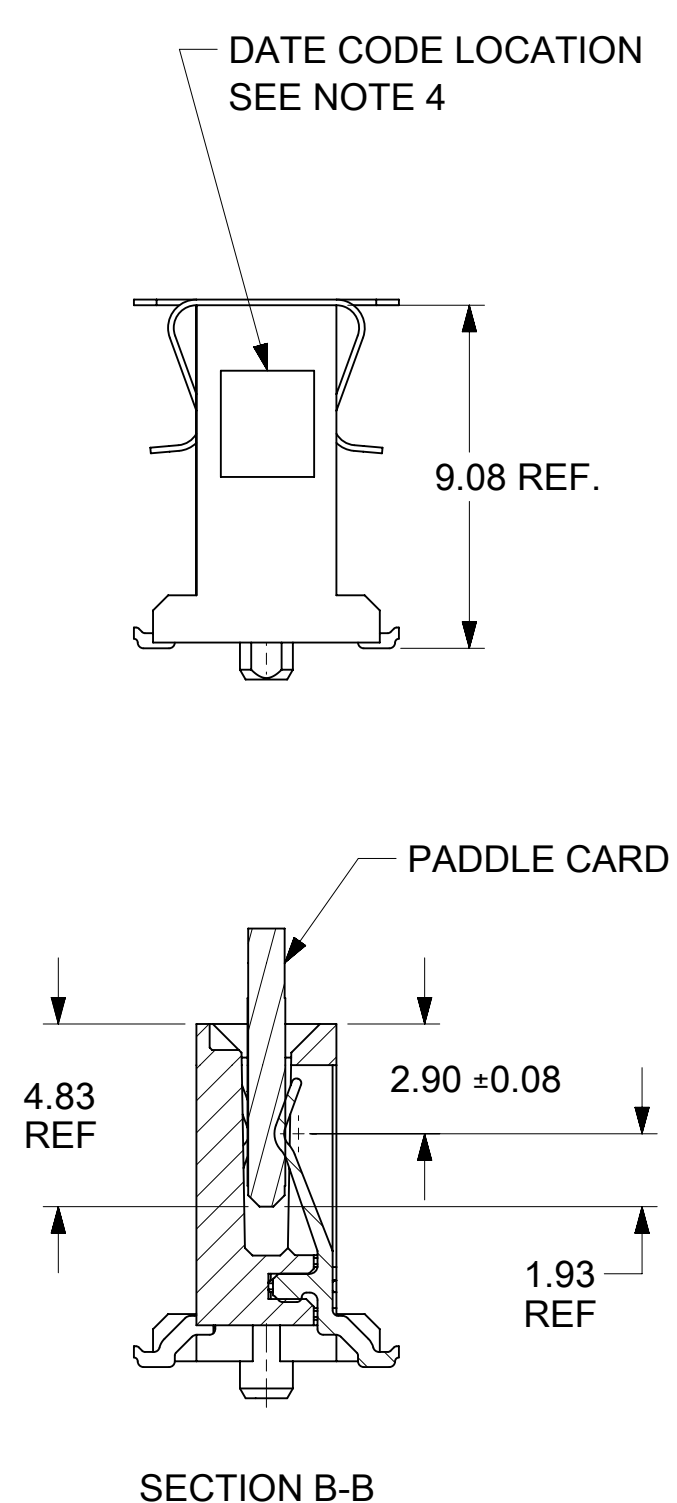




36 CIRCUIT ASSEMBLY SHOWN



- NOTES:
- MATERIAL:  
HOUSING - HIGH TEMPERATURE THERMOPLASTIC GLASS FILLED, UL 94V-0, BLACK  
TERMINALS - COPPER ALLOY
  - TERMINAL PLATING:  
OPTION 1  
CONTACT AREA: 0.38μm HARD GOLD OVER 2.54μm NICKEL  
SOLDER AREA: 2.54-5.09μm TIN OVER 1.27μm NICKEL  
OPTION 2  
CONTACT AREA: 0.76μm HARD GOLD OVER 2.54μm NICKEL  
SOLDER AREA: 2.54-5.09μm TIN OVER 1.27μm NICKEL
  - TERMINAL SOLDER FEET TO BE COPLANAR WITHIN 0.10/004 MEASURED FROM FRONT HOUSING STANDOFF (DATUM E)
  - DATE CODE: 4 DIGIT (3 DIGIT DAY, 1 DIGIT YEAR)
  - CIRCUIT IDENTIFIER: SEE APPROPRIATE INDUSTRY SPECIFICATION FOR LOCATION OF PIN 1
  - MATES WITH:  
A. INTERNAL CABLE SERIES:  
79575/74563/79576/74573/79536/74562/74569/74586  
B. PADDLE CARD PCB: DO NOT BOTTOM OUT PCB IN THE CONNECTOR. SEE SECTION Z-Z.  
USE WITH APPROPRIATE INTERNAL SHELL FROM SD-76010-002
  - LITTLE ROCK PACKAGING PER PK-75577-001  
CHENGDU PACKAGING PER PK-75577-002
  - CONFORMS TO PRODUCT SPECIFICATION PS-75783-001
  - CONFORMS TO APPLICATION SPECIFICATION AS-75783-001

| CIRCUIT SIZE | MAT'L NUMBER | PLATING OPTION | DIM 'A' | DIM 'B' | DIM 'C' |
|--------------|--------------|----------------|---------|---------|---------|
| 26           | 75577-1001   | OPTION 1       | 13.40   | 11.80   | 12.00   |
| 26           | 75577-1005   | OPTION 2       | 13.40   | 11.80   | 12.00   |
| 36           | 75577-1002   | OPTION 1       | 17.40   | 15.80   | 16.00   |
| 36           | 75577-1006   | OPTION 2       | 17.40   | 15.80   | 16.00   |
| 50           | 75577-1003   | OPTION 1       | 23.00   | 21.40   | 21.60   |
| 50           | 75577-1007   | OPTION 2       | 23.00   | 21.40   | 21.60   |
| 68           | 75577-1004   | OPTION 1       | 30.20   | 28.60   | 28.80   |

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

DIMENSION UNITS

mm

SCALE

5:1

GENERAL TOLERANCES (UNLESS SPECIFIED)

|                                                         | MM      | INCH |
|---------------------------------------------------------|---------|------|
| 4 PLACES                                                | ±       | ±    |
| 3 PLACES                                                | ±       | ±    |
| 2 PLACES                                                | ± 0.13  | ±    |
| 1 PLACE                                                 | ± 0.25  | ±    |
| 0 PLACES                                                | ±       | ±    |
| ANGULAR TOL                                             | ± 0.5 ° |      |
| DRAFT WHERE APPLICABLE<br>MUST REMAIN WITHIN DIMENSIONS |         |      |

CURRENT REV DESC: OBSOLETE PART NUMBER  
AS PER PCN#510579

EC NO: 675088

DRWN: SUGEEB

CHK'D: GGA

APPR: GGA

2021/08/02

2021/09/08

2021/09/08

INITIAL REVISION:

DRWN: JLSWENSON

APPR: MBANAKIS

06/07/07

06/07/07

THIRD ANGLE PROJECTION

C-SIZE

DRAWING

SERIES

75577

SALES DRAWING

IPASS VERTICAL CONNECTOR .8 MM PITCH I/O

PRODUCT CUSTOMER DRAWING

DOCUMENT NUMBER

SD-75577-002

DOC TYPE

PSD

DOC PART

001

REVISION

E

MATERIAL NUMBER

CUSTOMER

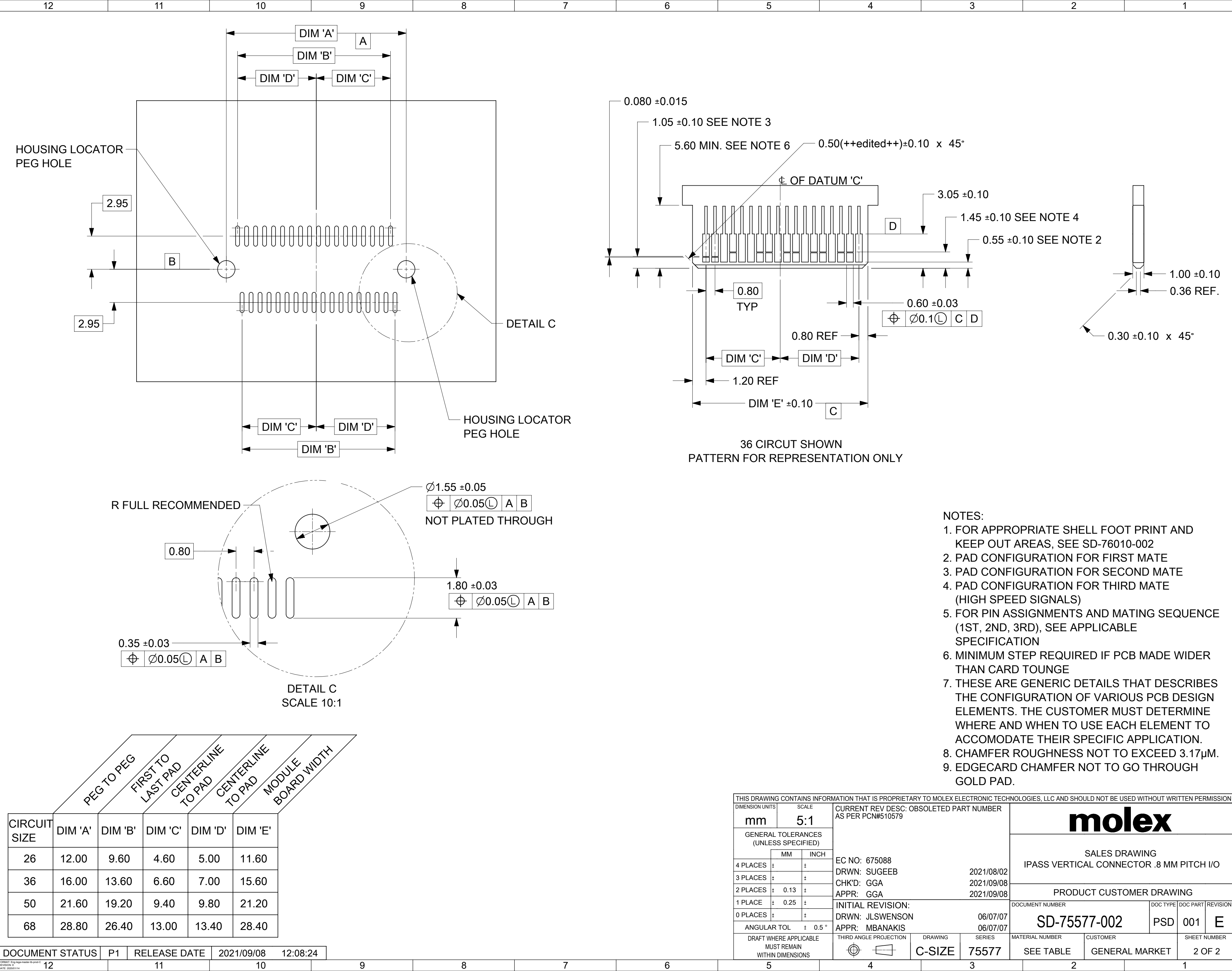
SHEET NUMBER

SEE TABLE

GENERAL MARKET

1 OF 2

| DOCUMENT STATUS | P1 | RELEASE DATE | 2021/09/08 | 12:08:24 |
|-----------------|----|--------------|------------|----------|
|-----------------|----|--------------|------------|----------|



- NOTES:
1. FOR APPROPRIATE SHELL FOOT PRINT AND KEEP OUT AREAS, SEE SD-76010-002
  2. PAD CONFIGURATION FOR FIRST MATE
  3. PAD CONFIGURATION FOR SECOND MATE
  4. PAD CONFIGURATION FOR THIRD MATE (HIGH SPEED SIGNALS)
  5. FOR PIN ASSIGNMENTS AND MATING SEQUENCE (1ST, 2ND, 3RD), SEE APPLICABLE SPECIFICATION
  6. MINIMUM STEP REQUIRED IF PCB MADE WIDER THAN CARD TOUNGE
  7. THESE ARE GENERIC DETAILS THAT DESCRIBES THE CONFIGURATION OF VARIOUS PCB DESIGN ELEMENTS. THE CUSTOMER MUST DETERMINE WHERE AND WHEN TO USE EACH ELEMENT TO ACCOMODATE THEIR SPECIFIC APPLICATION.
  8. CHAMFER ROUGHNESS NOT TO EXCEED 3.17µM.
  9. EDGE CARD CHAMFER NOT TO GO THROUGH GOLD PAD.

|              | PEG TO PEG         |         |         |         |         |
|--------------|--------------------|---------|---------|---------|---------|
|              | FIRST TO LAST PAD  |         |         |         |         |
|              | CENTERLINE TO PAD  |         |         |         |         |
|              | CENTERLINE TO PAD  |         |         |         |         |
|              | MODULE BOARD WIDTH |         |         |         |         |
| CIRCUIT SIZE | DIM 'A'            | DIM 'B' | DIM 'C' | DIM 'D' | DIM 'E' |
| 26           | 12.00              | 9.60    | 4.60    | 5.00    | 11.60   |
| 36           | 16.00              | 13.60   | 6.60    | 7.00    | 15.60   |
| 50           | 21.60              | 19.20   | 9.40    | 9.80    | 21.20   |
| 68           | 28.80              | 26.40   | 13.00   | 13.40   | 28.40   |

| DOCUMENT STATUS | P1 | RELEASE DATE | 2021/09/08 | 12:08:24 |
|-----------------|----|--------------|------------|----------|
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